



SPECIFICATION

OF PRODUCTS

PRODUCT NAME : DIELECTRIC CERAMIC FILTER

PART NUMBER : ECS-DCF-107

| Approved by | Checked by | Drawn by |
|-------------|-------------|----------|
| D. Kelly | A. Anderson | I. Lee |

ECS Inc. International

15351 W .109th Street, Lenexa, Kansas 66219

Tel : 1-913-782-7787

Fax : 1-913-782-6991

Web : www.ecsxtal.com



ECS Inc. International

| Part Number Sheet | |
|--------------------------|-------------|
| Customer | |
| Supplier P/N | ECS-DCF-107 |
| Customer P/N | |

| Customer's Approval Certificate | |
|--|--|
| Checked & Approval by | |
| Date | |

| Version | Reason Of Modification | Modification | Drawn | Checked | Approval | Date |
|---------|------------------------|--------------|-------|---------|----------|------|
| | | | | | | |
| | | | | | | |
| | | | | | | |

Please return this copy after signing as a certification of your approval.



ECS Inc. International

1. SCOPE

This specification shall cover the characteristics of the dielectric ceramic filter with the type ECS-DCF-107.

2. PART NO.

| |
|------------------|
| PART NUMBER |
| ECS-DCF-107 |
| CUSTOMER PART NO |
| |

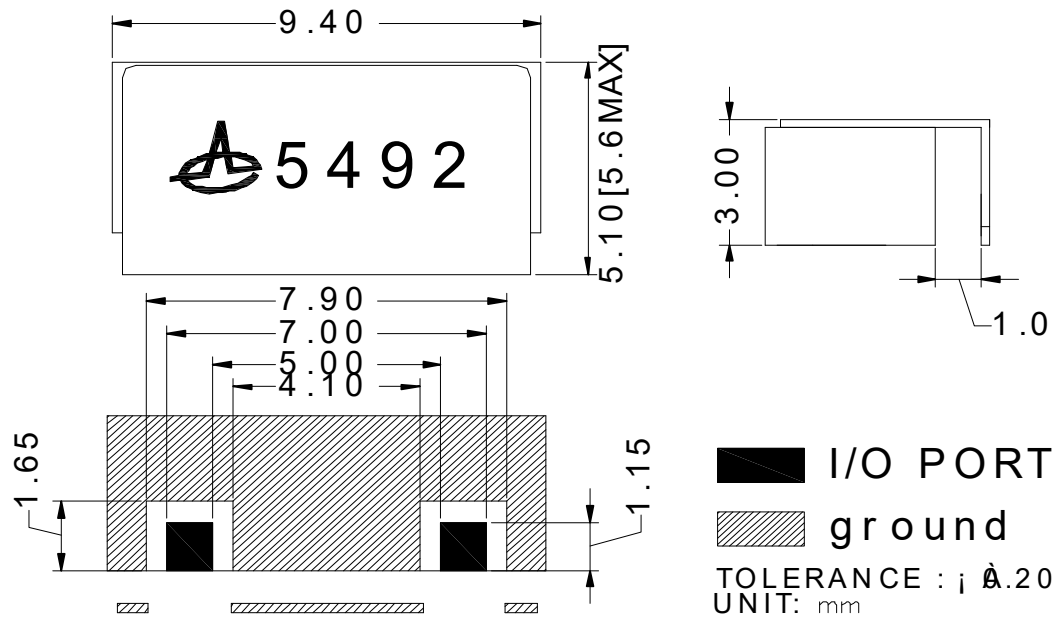
3. OUTLINE DIMENSIONS AND MARK

3.1 Appearance: No visible damage and dirt.

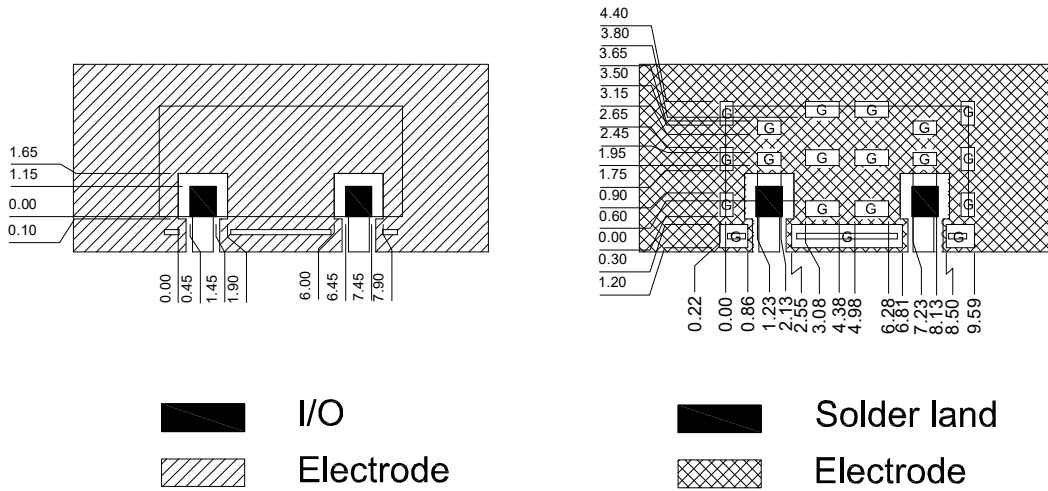
3.2 Construction: SMD dielectric ceramic Monoblock.

3.3 The products conform to the RoHS directive and national environment protection law.

3.4 Dimensions and mark

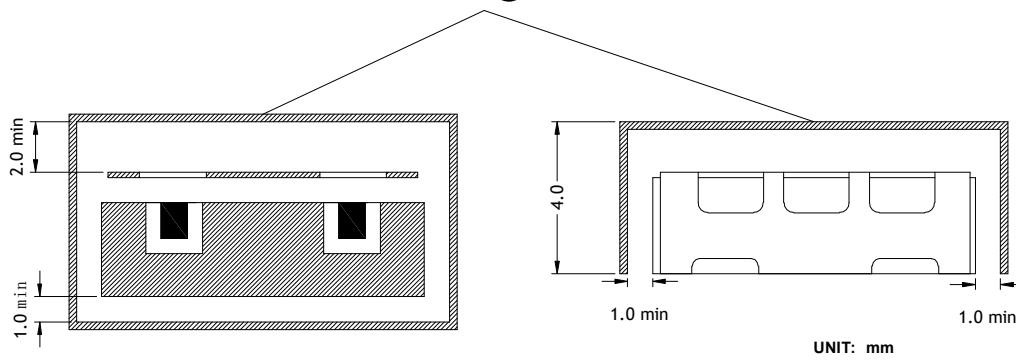


3.5 RECOMMENDED PC BOARD PATTERN

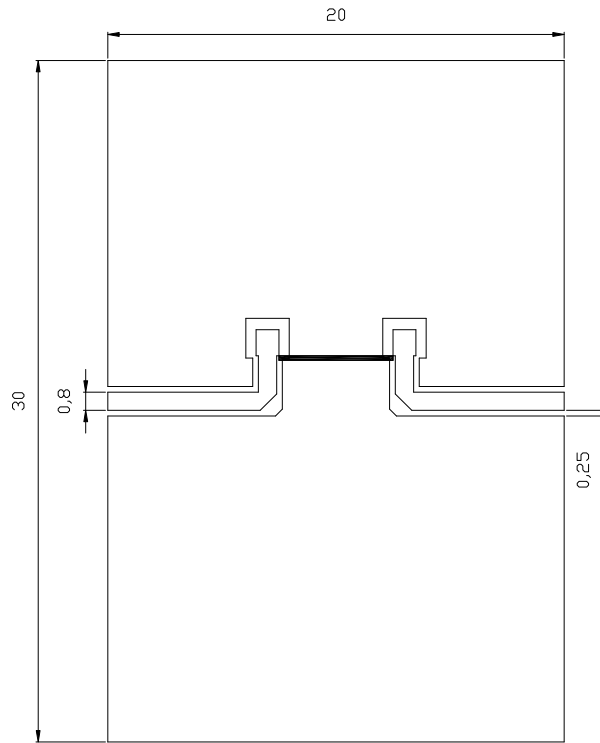


3.6 The recommended shielding case layout guide (min)

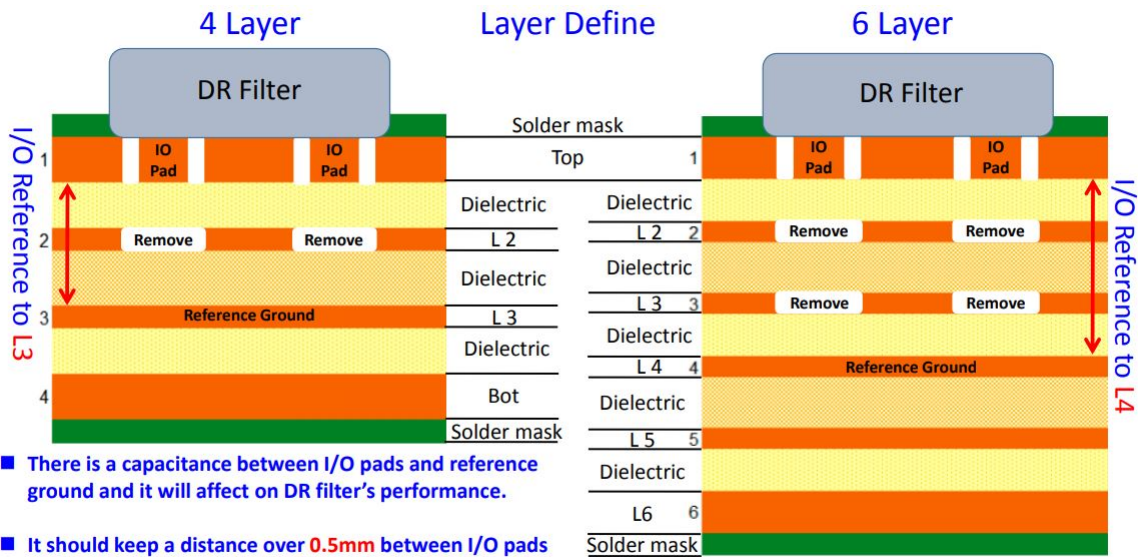
shielding case



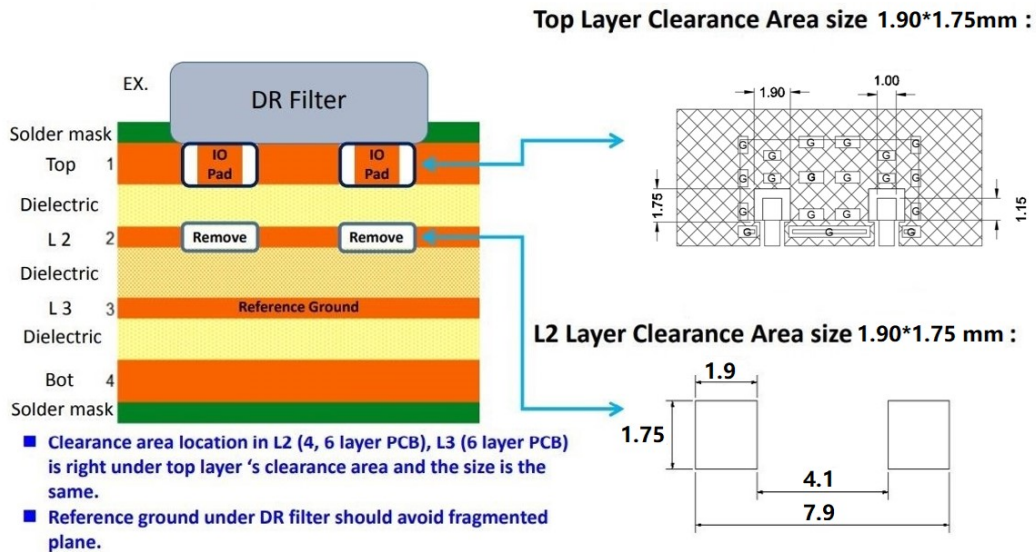
3.7 EVB CHARACTERISTICS



3.8 Reference Layer of Multiple Layer Stack up



3.9 Clearance Area



4.1 RATING

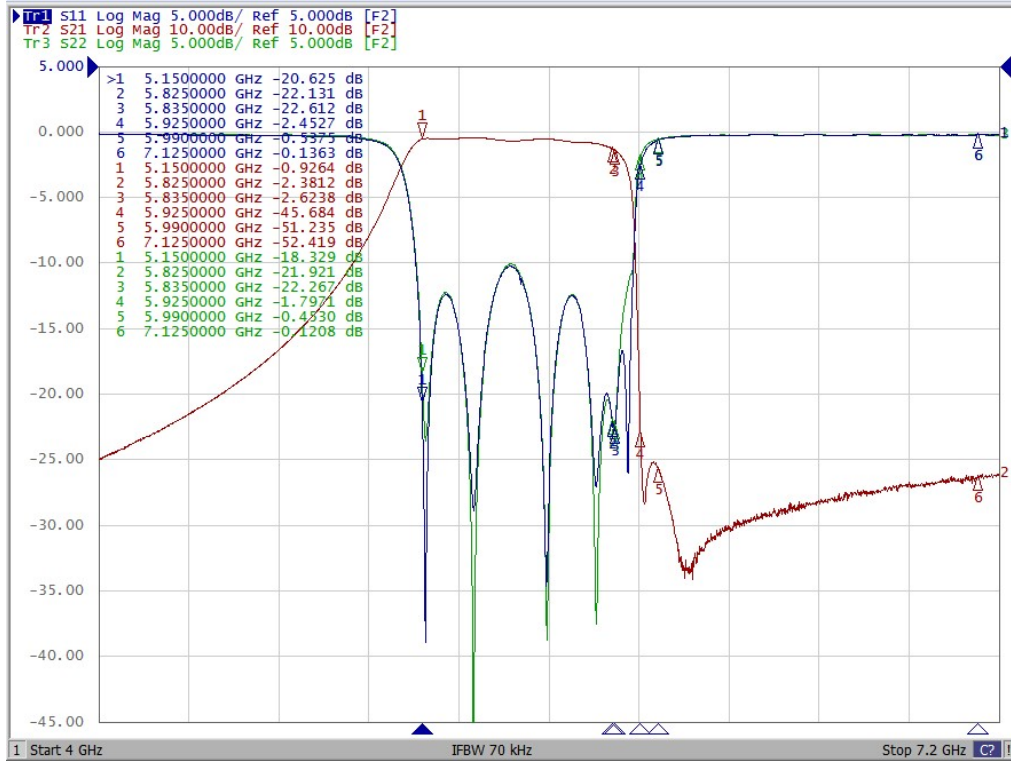
| Items | Requirement |
|--------------------------------|--------------------|
| Withstand DC Voltage | 50V (1min max) |
| Insulation Resistance MΩ min. | 100 (10V, 1min±5s) |
| Storage temperature | -40 ~ +85°C |
| Operation Temperature Range °C | -40 ~ +85°C |

4.2 ELECTRICAL SPECIFICATIONS

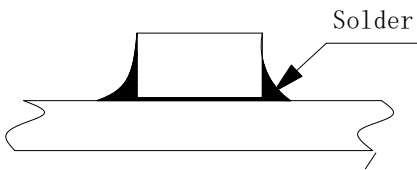
| Items | Requirement |
|------------------------------------|------------------------|
| Center frequency MHz | 5492.5 |
| Bandwidth [BW] MHz | 5150-5835 |
| Insertion Loss in BW dB max | 3.0@5825-5835@25°C |
| | 2.7@5150-5825@25°C |
| | 3.5@5825-5835@-40~85°C |
| | 3.2@5150-5825@-40~85°C |
| Ripple in BW dB max | 2.5 |
| Return Loss in BW dB min | 9.0 |
| Attenuation[Absolute Value] dB min | 45.0 @ 5925-5990 MHz |
| | 50.0 @ 5990-7125 MHz |
| Input Power W max. | 1 |
| In/Out Impedance ohm | 50 |



4.3 CHARACTERISTIC CURVE



5 ENVIRONMENTAL TESTS

| No. | Item | Test Condition | Remark |
|-----|----------------------------|---|--|
| 5.1 | Humidity Test | The device is subjected to 90%~95% relative humidity 40°C±2°C for 96h~98h, then dry out at 25°C±5°C and less than 65% relative humidity for 2h~4h. After drying out the device shall satisfy the specification in table 1. | It shall fulfill the specifications in Table 1. |
| 5.2 | High Temperature Exposure | The device shall satisfy the specification in table 1 after leaving at 85°C for 16h, provided it would be measured after 2h~4h leaving in 25°C±5°C and less than 65% relative humidity. | It shall fulfill the specifications in Table 1. |
| 5.3 | Low Temperature | The device shall satisfy the specification in table 1 after leaving at -40°C for 16h, provided it would be measured after 2h~4h leaving in 25°C±5°C and less than 65% relative humidity. | It shall fulfill the specifications in Table 1. |
| 5.4 | Temperature Cycle | Subject the device to -25°C for 30 min. followed by a high temperature of 85°C for 30 min cycling shall be repeated 5 times. At the room temperature for 1h~4h prior to the measurement. | It shall fulfill the specifications in Table 1. |
| 5.5 | Vibration | Subject the device to vibration for 2h each in x, y and z axis with the amplitude of 1.5mm, the frequency shall be varied uniformly between the limits of 10Hz~55Hz. | It shall fulfill the specifications in Table 1. |
| 5.6 | Soldering Test | The device should be satisfied after preheating at 120°C~150°C for 60seconds and dipping in soldering Sn an 260°C±5°C for 10±1 seconds. | Mechanical damage shall not occur. |
| 5.7 | Solder Ability | Dipped in 260°C±5°C solder bath for 3s±0.5 s with rosin flux (25wt% ethanol solution.) | The terminals shall be at least 95% covered by solder. |
| 5.8 | Terminal Pressure Strength |  <p>The device is subjected to be soldered to be soldered on test PCB. Then apply 5N of force for 10s±1s in the direction of the arrow.</p> | Mechanical damage such as breaks shall not occur. |

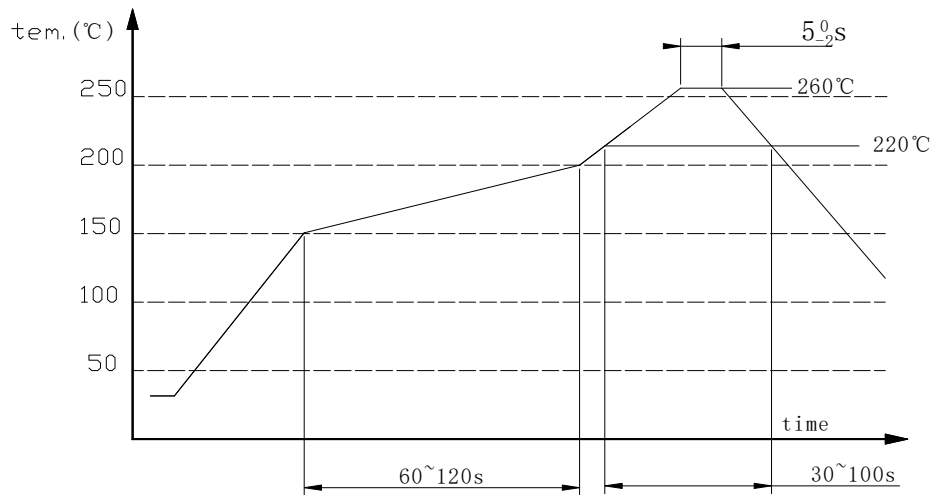


ECS Inc. International

Table 1

| Item | Characteristics after test |
|---|----------------------------|
| Insertion Loss Change dB max | ±0.3 |
| Ripple Change dB max | ±0.3 |
| Return loss. dB max | ±2.0 |
| Attenuation Change dB max | ±4.0 |
| Note: The limits in the above table are referenced to the initial measurements. | |

6. Recommended soldering conditions



| Phase | Profile features | Pb-Free Assembly |
|------------------------------------|--|----------------------------------|
| PREHEAT | -Temperature Min -Temperature Max -Time form | 150°C 200°C 60-120 seconds |
| RAMP-UP | Avg. Ramp-up Rate 200°C to 260°C | 3°C/second(max) |
| REFLOW | -Temperature -Total Time above 220°C | 220°C 30-100 seconds |
| PEAK | -Temperature -Time | 260°C 3-5 seconds |
| RAMP-DOWN | Rate | 2-6°C/second |
| Time from 25°C to Peak Temperature | | 8 minutes max |
| Composition of solder paste | | Ag3.0/Cu0.5/ Sn |



ECS Inc. International

7. OTHER

7.1 Caution

7.1.1 Don't apply excess mechanical stress to the component and terminals at soldering. Do not use this product with bend.

7.1.2 Do not clean or wash the component for it is not hermetically sealed.

7.1.3 Do not use strong acidity flux, more than 0.2wt% chlorine content, in flow soldering.

7.1.4 This specification mentions the quality of the component as a single unit. Please ensure the component is thoroughly evaluated in your application circuit

7.1.5 Expire date (Shelf life) of the products is six months after delivery under the conditions of a sealed and an unopened package. Please use the products within six months after delivery. If you store the products for a long time (more than six months), use carefully because the products may be degraded in the solderability or rusty. Please confirm solderability and characteristics for the products regularly.

7.1.6 Please contact us before using the product as automobile electronic component.

7.2 Notice

7.2.1 Please return one of these specifications after your signature of acceptance.